AMENDMENTS TO THE SPECIFICATION

Please replace page 14, lines 25-26 and page 15, lines 1-13 with the following paragraph rewritten in amendment format:

Subsequently, as shown in Fig. 8, the cavity 13 in the die set 1 is charged with molten resin 6 by an injection device. It should be noted that the injection device corresponds to the injection device 72 in Fig. 1. The molten resin 6 flows through the gate 14 before entering the cavity 13. At the same time, the power supplies 4 are activated by a controller which is a part of power supplies 4 so that electric currents are fed to the electrically powered heaters 3. Thus, the hold pins 2 are heated to a given temperature higher than the melting point of the resin. During the charging of the cavity 13 with the molten resin 6, since the insert 5 is fixedly supported by the hold pins 2, the insert 5 is prevented from moving due to a pressure and a flow resistance provided by the molten resin 6. Since the hold pins 2 are heated at the given temperature higher than the melting point of the resin, the molten resin 6 does not form solidified layers when encountering the hold pins 2.